

Product data sheet

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Features

- Ultra-Low capacitance:0.35pF(typ.)
- Reverse stand-off voltage:5V
- IEC 61000-4-2 (Air): ±15KV
 IEC 61000-4-2 (Contact): ±10KV

Pin Description

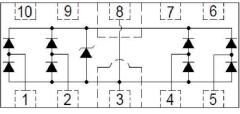


Applications

- USB 3.0, USB 2.0
- HDMI 1.3/1.4, Display Port 1.3, eSATA
- Unified Display Interface (UDI)
- Digital Visual Interface (DVI)
- High speed serial interfaces

10 9 8 7

Schematic Diagram



Top View

Limiting Values(T_A = 25 °C, unless otherwise specified)

Symbol	Parameter Conditions		Min	Max	Unit
	Electrostatic Discharge Voltage	IEC 61000-4-2; Contact Discharge	-	±10	kV
VESD		IEC 61000-4-2; Air Discharge	-	±15	kV
I _{PPM}	Rated Peak Pulse Current	t _P = 8/20 μs	-	2.5	А
T _A	Ambient Temperature Range	-	-55	125	°C
Tstg	Storage Temperature Range	-	-55	150	°C

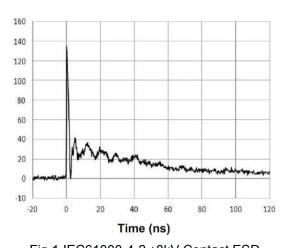


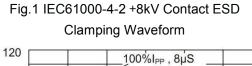


Symbol	Parameter	Conditions	Min	Тур.	Max	Unit
V_{RWM}	Reverse Working Voltage	T _A = 25 °C	-	-	5	V
V_{BR}	Breakdown Voltage	I _R = 1 mA	6	7.2	9.5	V
I _R	Reverse Leakage Current	V _{RWM} = 5V	-	0.01	1	μA
Vc	Clamping Valtage	I _{PP} =2.5A, T _P =8/20µs	-	10	-	V
	Clamping Voltage	V _{ESD} =+8kV	-	20	-	V
VT	Trigger Voltage	V _{ESD} =+8kV	-	135	-	V
CJ	lunction Consoitance	V_R = 0V, f = 1 MHz, I/O to I/O	-	0.15	-	pF
	Junction Capacitance	V_R = 0V, f = 1 MHz, I/O to GND	-	0.35	-	pF

Electrical Characteristics(T_A = 25 °C unless otherwise specified)

Typical Characteristics





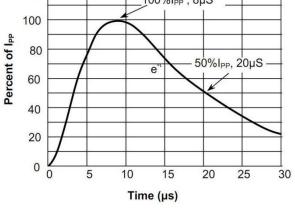


Fig.3 Pulse Waveform-8/20µs

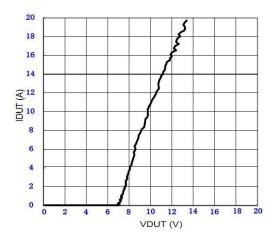
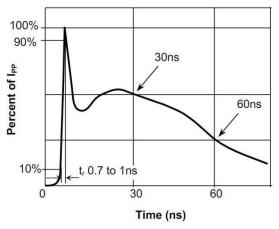


Fig.2 Transmission Line Pulse (t_P=100ns)

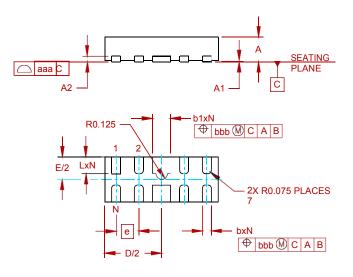




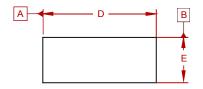




PACKAGE MECHANICAL DATA

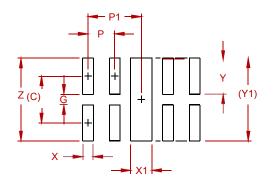


Dimensions in millimeters



DIMENSI ONS							
ЫМ	INCHES			MILLIN	MILLIMETERS		
	MIN	NOM	MAX	MIN	NOM	MAX	
Α	.020	.023	.026	0.50	0.58	0.65	
A1	0.00	.001	.002	0.00	0.03	0.05	
A2	(.005)		(0.13)				
b	.006	.008	.010	0.15	0.20	0.25	
b1	.014	.016	.018	0.35	0.40	0.45	
D	.094	.098	.102	2.40	2.50	2.60	
E	.035	.039	.043	0.90	1.00	1.10	
е	.020 BSC		0.50 BSC				
L	.012	.015	.017	0.30	0.38	0.425	
N	8		8				
aaa	.003			0.08			
bbb	.004			0.10			

Suggested Pad Layout



	DIMENSIONS				
DIM	INCHES	MILLIMETERS			
С	(.034)	(0.875)			
G	.008	0.20			
Р	.020	0.50			
P1	.039	1.00			
Х	.008	0.20			
X1	.016	0.40			
Y	.027	0.675			
Y1	(.061)	(1.55)			
Z	.061	1.55			

NOTES:

CONTROLLING DIMENSIONS ARE IN MILLIMETERS (ANGLES IN DEGREES). THIS LAND PATTERN IS FOR REFERENCE PURPOSES ONLY. CONSULT YOUR MANUFACTURING GROUP TO ENSURE YOUR COMPANY'S MANUFACTURING GUIDELINES ARE MET.

REEL SPECIFICATION

P/N	PKG	QTY
MS1045-04F	DFN2510P10E	3000



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